

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

## PCN# 20240930007.1 Datasheet for LMC648x

## Change Notification

Date: October 01, 2024 To: Newark/Farnell PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team SC Business Services

#### 20240930007.1 Data Sheet Change Notification Attachments

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER				
LMC6482AIN/NOPB	NULL				

Technical details of this Product Change follow on the next page(s).

PCN Number: 2024			0240930007.1					PCN Date:		October 01, 2024		
Title: Datasheet for LMC648x												
				inac	nagement team Dept: Q					Quality Services		
Pro	posed	l 1 <sup>st</sup> Ship Da				nber 30, 2024						
	nge 1					•						
		mbly Site				Design			Wafer Bump Material			
	Asse	mbly Process			$\boxtimes$	🛛 Datasheet			Wafer Bump Process			
		mbly Materia				Part number change			Wafer Fab Site			
		anical Specif				Test Site			Wafer Fab Materials			
	Packi	ng/Shipping/	'Label	ling		Test Process			Wafer Fab Process			
						PCN Det	aile					
Des	cripti	on of Chang	ie:			PCN Det	alis					
				beina i	inda	ated as summ	arized below					
						further details		•				
		ing energe i		,								
											LMC6482	
		AS TRUMENTS					Chicago		TOPED	DELICI	LMC6484	
-									TOBER 1997	- REVISE	ED SEPTEMBER 2024	
	-		-	-	-	o Revision J (S	-	-			Page	
						erence Amplifier ion ratio MIN fro						
						IN for LMC648xI						
						ction ratio MIN fr						
•	Update	d Figure 7-17,	Half-W	ave Rec	tifier	With Input Curre	nt Protection (F	Ri) to	illustrate	correct	circuit25	
2												
The datasheet number will be chan												
							ange To:					
	LMC648x SN			105	OS674I SN			OS674J				
Thes	se cha	nges may be	e revie	ewed at	: the	e datasheet lir	nks provided.					
http	://ww	w.ti.com/pro	duct/	LMC64	<u>82</u>							
Rea	son f	or Change:										
To a	ccura	tely reflect de	evice	charact	eris	stics. The data	sheet update	e is	driven b	by the	changes	
anno	ounce	d on PCN 202	24093	80009.			· · · · · · · · · · · · · · · · · · ·				-	
Anti	icipat	ed impact o	n Fit	, Form	, Fι	inction, Qua	lity or Relia	bili	t <mark>y (pos</mark> i	itive ,	/ negative):	
Elec	trical	specification	perfo	rmance	cha	anges as indic	ated above.					
Changes to product identification resulting from this PCN:												
None.												
Product Affected:												
Devices affected by changes in PCN 20240930009												
	LMC6482AIMX/NOPB LMC6484AIMX/NOPB LMC6482AIN/NOPB											
Data	ashee	et Only										
		IMX/J70005	22	MC649	2411	I/NOPB	LMC6482IM	MY/			482IMX/NOPB	
	CU+02	111/0000			7411	IN OF D		<u>пл/</u>		LINCO		

LMC6482IN/NOPB	LMC6484IMX/NOPB	LMC6484AIN/NOPB	

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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